

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: 98 P7501 US 01



17/D
(11/6/01)
B.H

In re the application of:)
Ramachandran et al.) Group Art: 1746
Serial No.: 09/204,706) Examiner: A. Olsen
Filing Date: December 3, 1998)
Title: REMOVAL OF POST-RIE POLYMER)
ON Al/Cu METAL LINE)

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Box CPA
Washington, D.C. 20231

Sir:

In advance of prosecution and before the application is taken up for examination on the merits, it is respectfully requested that the claims be amended as follows:

IN THE CLAIMS:

13. (Twice Amended) In a metal etch tool for removing post-RIE polymer rails formed on a Al/Cu metal line of a semiconductor structure, the improvement comprising an integrated metal etch tool comprising therein: [separate]

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a) strip chamber means [for forming a water-only plasma process] to strip the photo-resist layer of a semiconductor composite structure with water only plasma subsequent [previously subjected] to a RIE